

**TABLE 2.** Current state of rigid substrate technology for package and module boards.

	<b>CONVENTIONAL</b>  Available from 85% of industry fabricators	<b>LEADING EDGE</b> (Limited Production) Available from 15% of industry fabricators	<b>STATE OF THE ART</b>  Available from less than 1% of industry fabricators
	<b>FR-4</b>	<b>High Temp FR-4 RoHS compliant</b>	<b>High Td Epoxy with low loss</b>
Conductor width/ line space (µm)	75/75	50/50	40/40
PTH hole size, unplated (µm)	150	120	75
Drill capture land size (µm)	350	240	150
Buried passive components	N/A	Yes	Yes